

LISTING OF THE CLAIMS:

Claims 1-50 (Cancelled)

51. (New) A method for electrically stressing through a specified voltage at least one semiconductor chip on wafers for controlled contactless burn-in, voltage screen and reliability evaluation of product wafers, said method comprising:

applying said voltage to said at least one chip for the probing thereof in the absence of physically contacting the chip surface; and

providing a rectangular core of non-magnetic material having electrical wire coils wound thereabout, connecting said wire coils to decal masks on a plurality of said wafers positioned centrally on said core, each said decal mask being provided to conduct a generated voltage to a chip under said mask.

52. (New) A method as claimed in Claim 51, wherein said magnetically induced voltage utilizes a time-varying magnetic field.

53. (New) A method as claimed in Claim 51, wherein each said coil is conducted to a time-varying voltage source so as to generate a magnetic field perpendicular to the surface of each said wafer in the center of said non-magnetic core.

54. (New) A method as claimed in Claim 53, wherein electrical wires extend from each said mask to a panel for the direct measurements and verification of the direct voltages present on each of said wafer.

55. (New) A method as claimed in Claim 51, wherein said non-magnetic core is constituted of wood.